

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	394	interposer with capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:07
S2	355	S1 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:03
S3	276	S2 and (bump solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:33
S4	149	S2 and (bump solder)	USPAT	OR	ON	2005/08/07 15:33
S5	3	("5903050" "5937493" "6384468").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:34
S6	48	("5519576" "5672909" "5691568").PN. OR ("5903050").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:35
S7	35	("4225468" "4300115" "4332341" "4626804" "4654628" "4658234" "4712161" "4945399" "5216404" "5379190" "5539186" "5557502" "5621619" "5629838" "5635767" "5636099" "5661450" "5726485" "5729438" "5745334" "5760662" "5796587" "5870274" "5903050" "5923077" "5977863" "6005777" "6097277" "6103146" "6124634").PN. OR ("6326677").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:38
S8	61	teflon with elasticity with modul\$5	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:39
S9	0	teflon near2 "Young's" adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:40
S10	0	teflon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:40

S11	121220	teflon wiht Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:43
S12	16	teflon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:40
S13	857	silicon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:43
S14	68	silicon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 15:44
S15	17	("6222246").URPN.	USPAT	OR	ON	2005/08/07 15:47
S16	44335	layer near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:55
S17	18533	S16 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:50
S18	23	interposer with S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:03
S19	31886	film near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:02
S20	20	interposer with S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:55
S21	21900	substrate near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:02

S22	6306	substrate with S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:03
S23	3545	S22 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:03
S24	186	interposer with capacit\$5	USPAT	OR	ON	2005/08/07 16:40
S25	0	capacitive adj layer with interposer	USPAT	OR	ON	2005/08/07 16:40
S26	0	capacitive adj layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:40
S27	2	capacitive near2 layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:16
S28	53	("4202007" "4322778" "4328530" "4349862" "4489364" "4688151" "4744008" "4803595" "4811082" "4866507" "4926241").PN. OR ("5177594"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 16:47
S29	1	"5177594".PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 16:47
S30	1	S29 AND capac\$8	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 16:47
S31	53	("4202007" "4322778" "4328530" "4349862" "4489364" "4688151" "4744008" "4803595" "4811082" "4866507" "4926241").PN. OR ("5177594"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/07 16:58
S32	19937	motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:17

S33	27	motherboard with PCB WITH interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:18
S34	235	motherboard WITH interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:19
S35	91	motherboard WITH interposer	USPAT	OR	ON	2005/08/07 18:21
S36	0	motherboard WITH leve	USPAT	OR	ON	2005/08/07 18:21
S37	321	motherboard WITH level	USPAT	OR	ON	2005/08/07 18:22
S38	0	mother adj board WITH last with level	USPAT	OR	ON	2005/08/07 18:22
S39	8	mother adj board WITH last	USPAT	OR	ON	2005/08/07 18:23
S40	1364	motherboard and "257"/\$.ccls.	USPAT	OR	ON	2005/08/07 18:24
S41.	174	S40 and interposer	USPAT	OR	ON	2005/08/07 18:24